

Title (en)
Method of forming solder mask

Title (de)
Verfahren zur Herstellung einer Lötstopmmaske

Title (fr)
Procédé de formation d'un masque de soudure

Publication
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Application
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Priority
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Abstract (en)
The invention relates to a method of forming a solder mask on a printed circuit board using a powder paint composition, which method comprises the steps of: charging powder paint particles in the presence of carrier particles; feeding the charged powder paint particles with carrier particles to a transporter; optionally transferring the charged powder paint particles from the transporter onto a transfer medium; applying the powder paint particles to a printed circuit board to form a layer of powder paint particles; irradiating the layer by subjecting the layer to ultra violet irradiation through a pattern mask to obtain partial or full cure of the exposed powder paint particles; developing the layer with a medium which dissolves the region not irradiated by the ultraviolet rays.

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IPC 8 full level
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Citation (search report)
• [Y] EP 0286594 A2 19881012 - CIBA GEIGY AG [CH]
• [DY] US 6342273 B1 20020129 - HANDELS JOHANNES W H [NL], et al
• [A] US 2003170568 A1 20030911 - MISEV TOSKO A [US], et al
• [A] WO 03043392 A1 20030522 - ARRAY AB [SE], et al
• [A] US 4592816 A 19860603 - EMMONS WILLIAM D [US], et al

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